

Diodes type D61 are of modern design with internal spring loaded contacts, high alumina ceramic insulator and pressure welded encapsulation. Designed for use in power electronic circuits and equipment under normal operating conditions.

**KEY PARAMETERS**

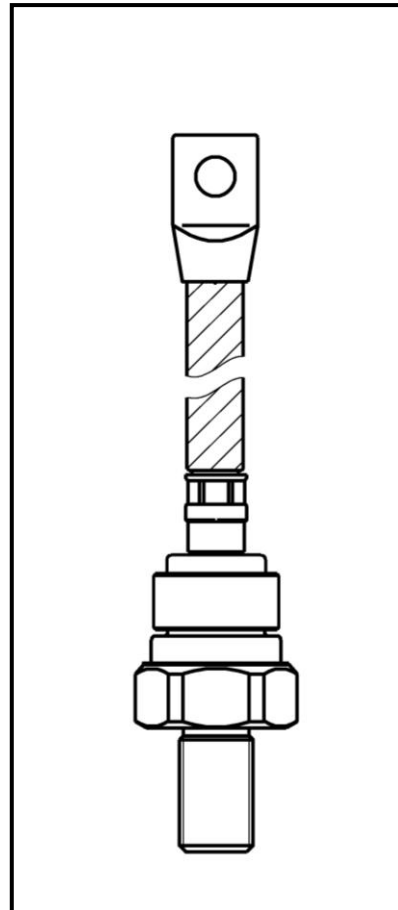
$U_{RRM}$	up to 3200 V
$I_{F(AV)}$	250 A
$I_{FSM}$	5500 A

**FEATURES**

- all diffused design
- high current capabilities
- high surge current capabilities
- high rates voltages
- low thermal impedance
- tested according to IEC standards
- compact size and small weight

**APPLICATION**

- High Voltage Power Supplies
- Motor Control
- Battery Chargers
- Free Wheeling Diode
- Resistance Welding



Outline type code: JEDEC DO-205AB

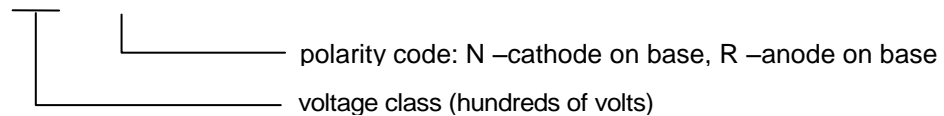
See package details for further information

Designed for use in high power industrial and commercial power electronic circuits and equipment where high currents are encountered and high reliability is essential.

**ORDERING INFORMATION**

When ordering please refer to device code builder presented below.  
Please use the complete part number when ordering, quote or in any future correspondence relating to your order.

**D61-250-□□-□0**



**ELECTRICAL PARAMETERS**

**Voltage ratings**

Voltage class	$U_{RRM}$	$U_{RSM}$	$I_{RRM}$
	V	V	mA
18	1800	1900	50
20	2000	2100	
22	2200	2300	
24	2400	2500	
26	2600	2700	
28	2800	2900	
30	3000	3100	
32	3200	3300	

**Electrical properties**

Parameter		Unit	Test conditions	Value
Average forward current @ case temperature	$I_{F(AV)}$	A		250
	$T_c$	°C		125
RMS forward current	$I_{F(RMS)}$	A		395
Surge current	$I_{FSM}$	A	$T_j=T_{jmax}$ , $U_R=0,8U_{RRM}$ , $t_p=10ms$	5500
$I^2t$ – value	$I^2t$	kA <sup>2</sup> s		150
Forward voltage drop max.	$U_{FM}$	V	$T_j=25^\circ C$ , $I_{FM}=800A$	1,60
Threshold voltage	$U_{F(T0)}$	V		0,70
Slope resistance	$r_F$	mΩ		1,22

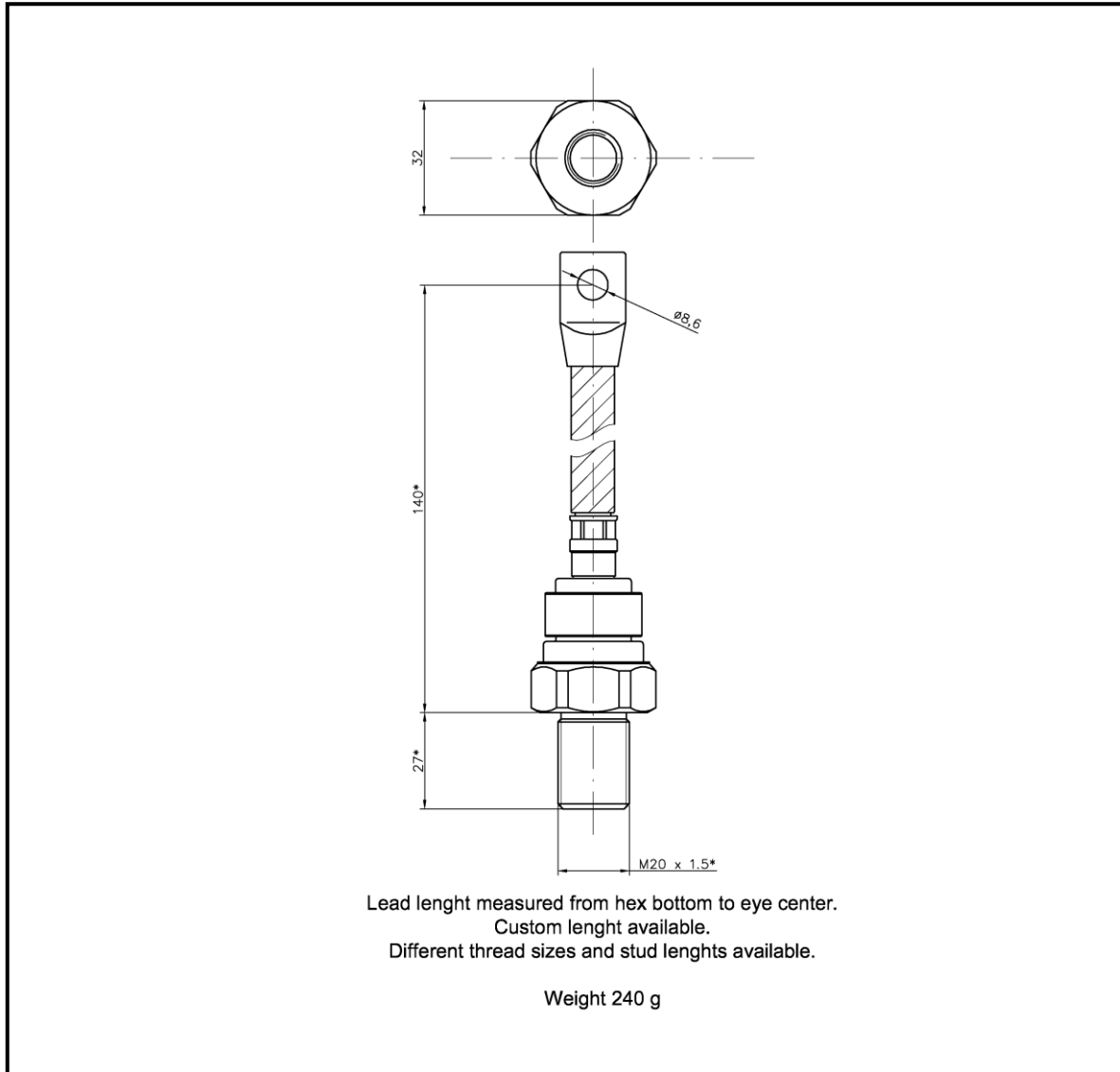
**Thermal properties**

Parameter		Unit	Test conditions	Value
Thermal resistance, junction to case	$R_{thJC}$	°C/W	DC	0,12
Thermal resistance, case to heatsink	$R_{thCS}$	°C/W		0,10
Operating junction temperature	$T_{jmin} \dots T_{jmax}$	°C		-40...+175
Storage temperature	$T_{stg}$	°C		-40...+175

**Mechanical properties**

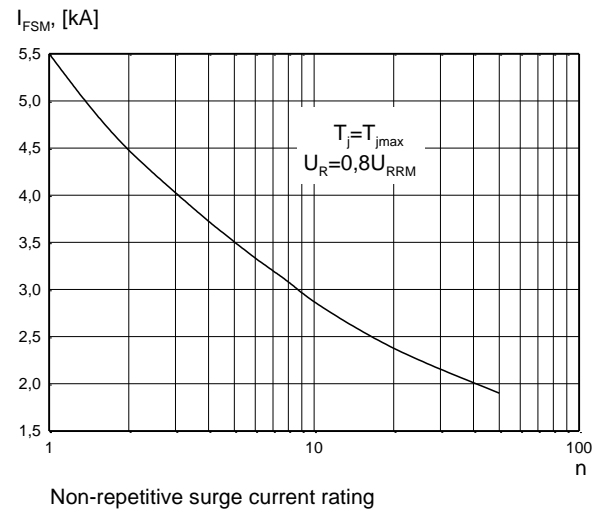
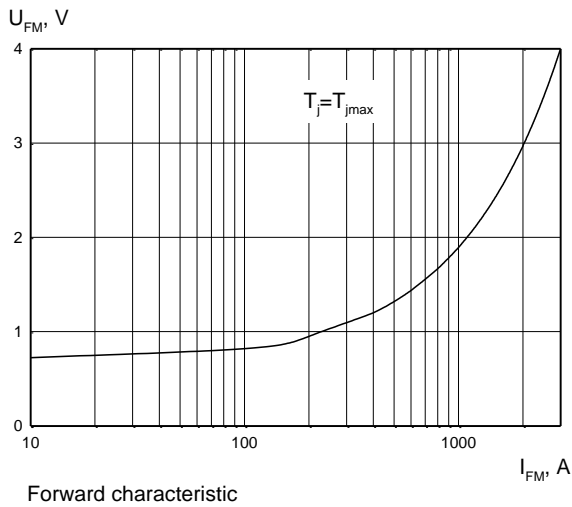
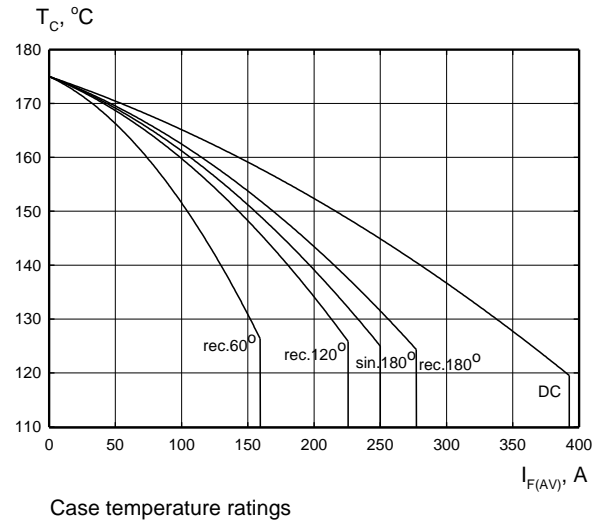
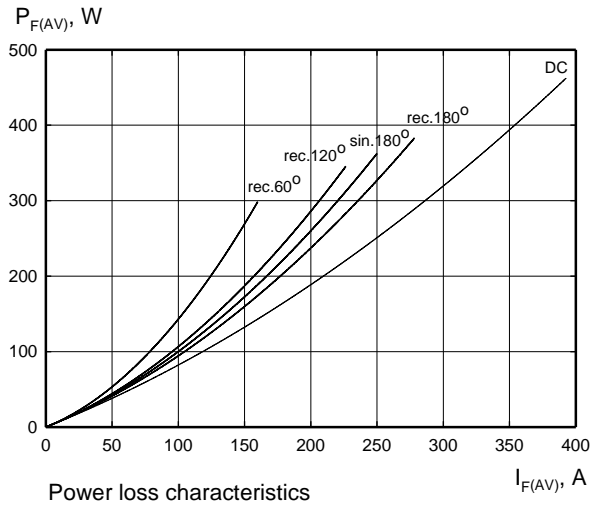
Parameter		Unit	Value
Mounting torque	M	Nm	28 ... 32
Weight	m	g	240

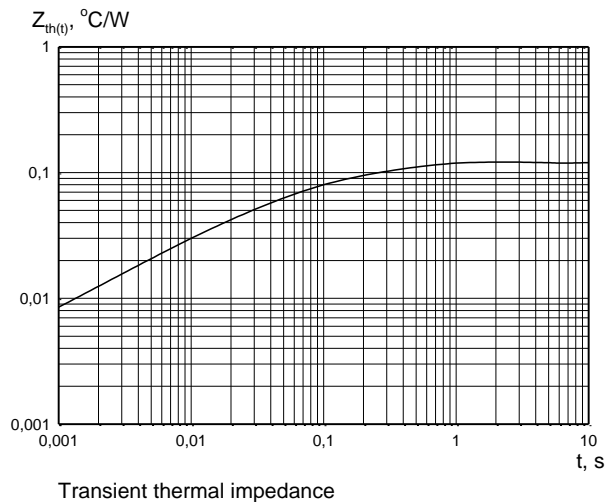
**Package details**



For further package information, please contact Sales & Marketing Department. All dimensions in mm, unless stated otherwise.  
Do not scale.

**CHARACTERISTICS**





## HEATSINKS

**KUBARA LAMINA SA** has its own proprietary range of extruded aluminium heatsinks designed to optimise the performance of our semiconductors with natural and forced air flow.

## POWER ASSEMBLY CAPABILITY

**KUBARA LAMINA SA** provides a support for those customers requiring more than a basic semiconductor and offers precisely assembled Power Blocks according to factory or customer standards.